



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SERIES: MJ-3536NG | **DESCRIPTION:** MID MOUNT POWER JACK

FEATURES

- isolated ground pin
- internal tip switch


SPECIFICATIONS

parameter	conditions/description	min	typ	max	units
rated input voltage			12		Vdc
rated input current				1	A
contact resistance	between terminal and mating plug after life test, between terminal and mating plug between terminal in a closed circuit ¹ after life test, between terminal in a closed circuit ¹			50 100 30 60	mΩ mΩ mΩ mΩ
insulation resistance	at 500 Vdc at 500 Vdc, after environmental tests	100 50			MΩ MΩ
voltage withstand	at 50/60Hz for 1 minute			500	Vac
insertion/withdrawl force		0.3 0.2		3 2	kg kg
terminal strength	any direction for 10 seconds			500	g
operating temperature		-25		85	°C

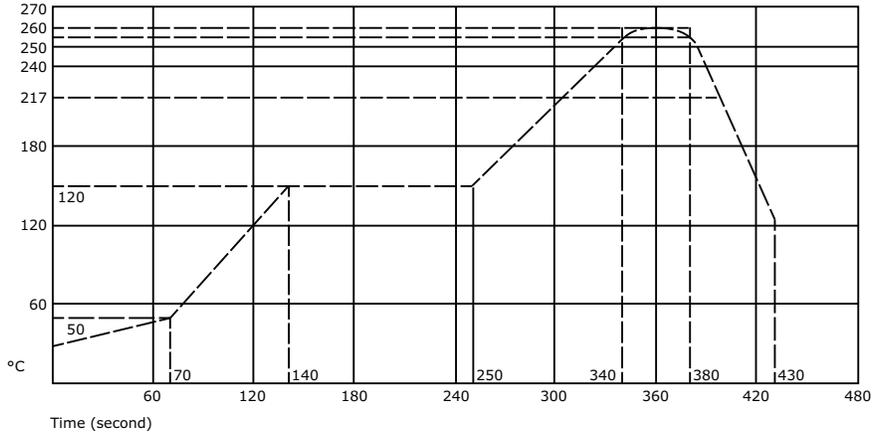
Notes: 1. When measured at a current of less than 100 mA / 1 kHz

TESTING

parameter	conditions/description	min	typ	max	units
solderability	95% solder coverage on lead, neutral flux, 2 sec.	235	240	245	°C
reflow soldering	see graph				
life	at 24 insertion/withdrawl cycles per minute		5,000		cycles
heat	the relative test before and after testing should comply with the Insulation Resistance section	83	85 96	87 50	°C % RH hours
cold	the relative test before and after testing should comply with the Insulation Resistance section	-33	-35 96	-37	°C hours
humidity	the relative test before and after testing should comply with the Insulation Resistance section	38	40 96	42 95	°C hours % RH

Notes: All measurements and test shall be made at a temperature 10°C to 35°C with a relative humidity of 45% RH to 85% RH under the standard atmospheric pressure unless otherwise specified.

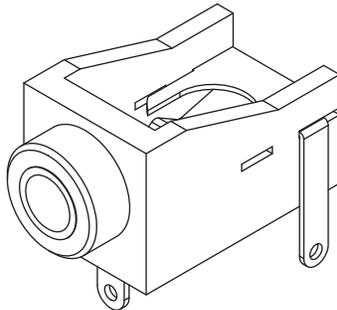
REFLOW SOLDERING



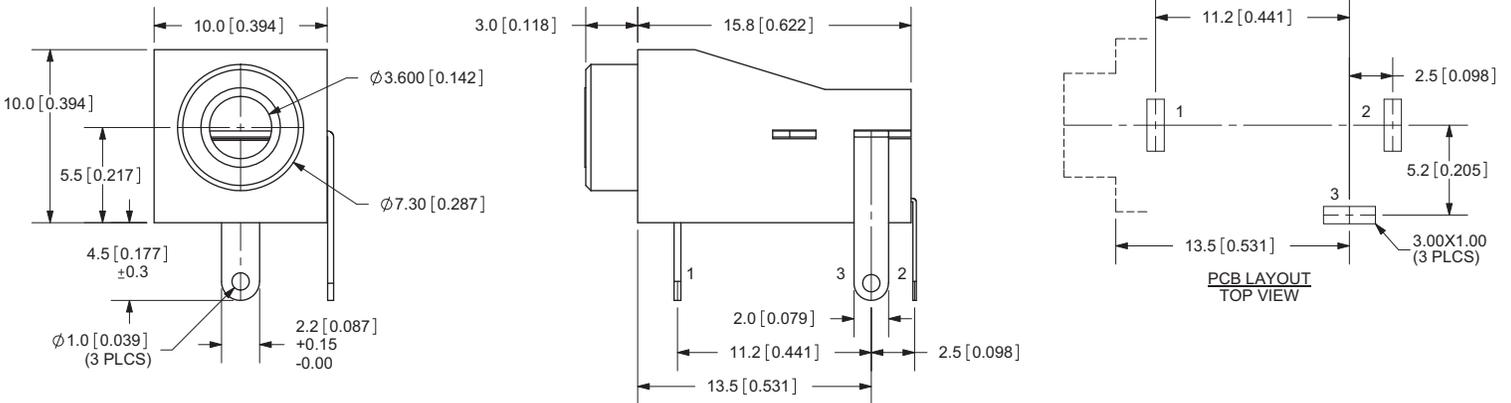
MECHANICAL DRAWING

units: mm[inches]
 tolerance:
 X.X ± 0.2mm
 X.XX ± 0.1mm
 X.XXX ± 0.05mm

MODEL NO.	MJ-3536NG
SCHEMATIC	



	MATERIAL	PLATING
plastic	PBT	
bushing	brass	nickel
terminal 1	brass	Tin
terminal 2	copper alloy	Tin
terminal 3	brass	Tin



REVISION HISTORY

rev.	description	date
1.0	initial release	07/29/2011

The revision history provided is for informational purposes only and is believed to be accurate.



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CUI offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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CUI products are not authorized or warranted for use as critical components in equipment that requires an extremely high level of reliability. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.